Triacs

HS137S series
HS137M series

GENERAL DESCRIPTION

Glass passivated triacs in a plastic envelope, suitable for surface mounting, intended for use in applications requiring high bidirectional transient and blocking voltage capability and high thermal cycling performance. Typical applications include motor control, industrial and domestic lighting, heating and static switching.

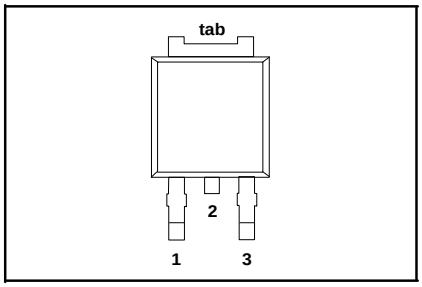
QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	MAX.	MAX.	UNIT
	HS137S (or HS137M)-	**500**	**600**	**800**	
	HS137S (or HS137M)-	**500F**	**600F**	**800F**	
	HS137S (or HS137M)-	**500G**	**600G**	**800G**	
V_{DRM}	Repetitive peak off-state voltages	500	600	800	V
$I_{T(RMS)}$	RMS on-state current	8	8	8	A
I_{TSM}	Non-repetitive peak on-state current	65	65	65	A

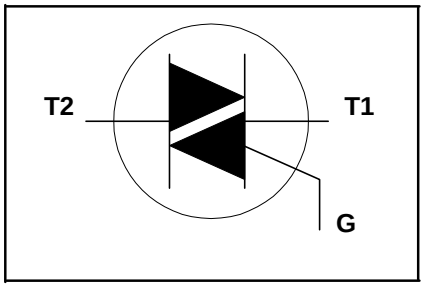
PINNING - SOT428

PIN NUMBER	Standard S	Alternative M
1	MT1	gate
2	MT2	MT2
3	gate	MT1
tab	MT2	MT2

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.			UNIT
				-500	**-600**	**-800**	
V_{DRM}	Repetitive peak off-state voltages		-	500[1]	600[1]	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 102$ ˚C	-	8			A
I_{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25$ ˚C prior to surge					
		t = 20 ms	-	65			A
		t = 16.7 ms	-	71			A
I^2t	I^2t for fusing	t = 10 ms	-	21			A^2s
dI_T/dt	Repetitive rate of rise of on-state current after triggering	I_{TM} = 12 A; I_G = 0.2 A; dI_G/dt = 0.2 A/µs					
		T2+ G+	-	50			A/µs
		T2+ G-	-	50			A/µs
		T2- G-	-	50			A/µs
		T2- G+	-	10			A/µs
I_{GM}	Peak gate current		-	2			A
V_{GM}	Peak gate voltage		-	5			V
P_{GM}	Peak gate power		-	5			W
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.5			W
T_{stg}	Storage temperature		-40	150			˚C
T_j	Operating junction temperature		-	125			˚C

1 Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 A/µs.

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$R_{th\ j\text{-}mb}$	Thermal resistance junction to mounting base	full cycle	-	-	2.0	K/W
		half cycle	-	-	2.4	K/W
$R_{th\ j\text{-}a}$	Thermal resistance junction to ambient	pcb (FR4) mounted; footprint as in Fig.14	-	75	-	K/W

STATIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.			UNIT
		HS137S-(or HS137M)			**...**	**...F**	**...G**	
I_{GT}	Gate trigger current	V_D = 12 V; I_T = 0.1 A	-	5	35	25	50	mA
		T2+ G+	-	8	35	25	50	mA
		T2+ G-	-	11	35	25	50	mA
		T2- G-	-	30	70	70	100	mA
I_L	Latching current	T2- G+						
		V_D = 12 V; I_{GT} = 0.1 A	-	7	30	30	45	mA
		T2+ G+	-	16	45	45	60	mA
		T2+ G-	-	5	30	30	45	mA
		T2- G-	-	7	45	45	60	mA
I_H	Holding current	T2- G+	-	5	20	20	40	mA
V_T	On-state voltage	V_D = 12 V; I_{GT} = 0.1 A	-	1.3	1.65			V
V_{GT}	Gate trigger voltage	I_T = 10 A	-	0.7	1.5			V
		V_D = 12 V; I_T = 0.1 A	0.25	0.4	-			V
I_D	Off-state leakage current	V_D = 400 V; I_T = 0.1 A; T_j = 125 ˚C	-	0.1	0.5			mA
		V_D = $V_{DRM(max)}$; T_j = 125 ˚C						

DYNAMIC CHARACTERISTICS

T_j = 25 ˚C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.			TYP.	MAX.	UNIT
		HS137S-(or HS137M)	**...**	**...F**	**...G**			
dV_D/dt	Critical rate of rise of off-state voltage	V_{DM} = 67% $V_{DRM(max)}$; T_j = 125 ˚C; exponential waveform; gate open circuit	100	50	200	250	-	V/µs
dV_{com}/dt	Critical rate of change of commutating voltage	V_{DM} = 400 V; T_j = 95 ˚C; $I_{T(RMS)}$ = 8 A; dI_{com}/dt = 3.6 A/ms; gate open circuit	-	-	10	20	-	V/µs
t_{gt}	Gate controlled turn-on time	I_{TM} = 12 A; V_D = $V_{DRM(max)}$; I_G = 0.1 A; dI_G/dt = 5 A/µs	-	-	-	2	-	µs

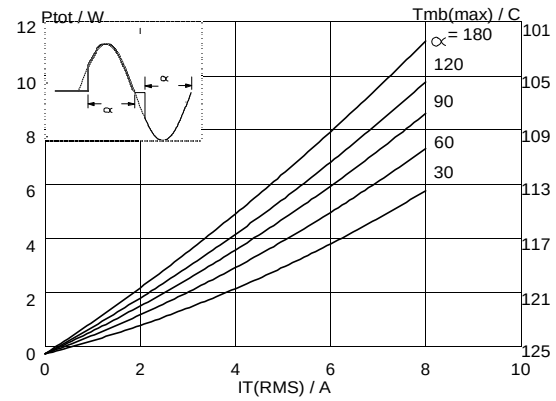


Fig.1. Maximum on-state dissipation, P_{tot}, versus rms on-state current, $I_{T(RMS)}$, where α = conduction angle.

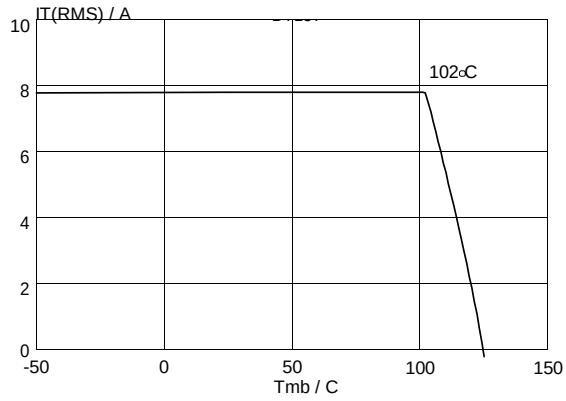


Fig.4. Maximum permissible rms current $I_{T(RMS)}$, versus mounting base temperature T_{mb}.

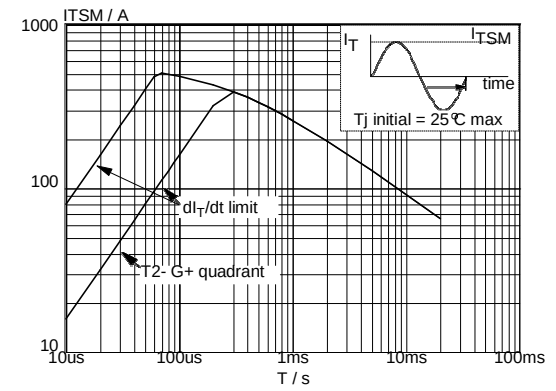


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus pulse width t_p, for sinusoidal currents, $t_p \leq 20ms$.

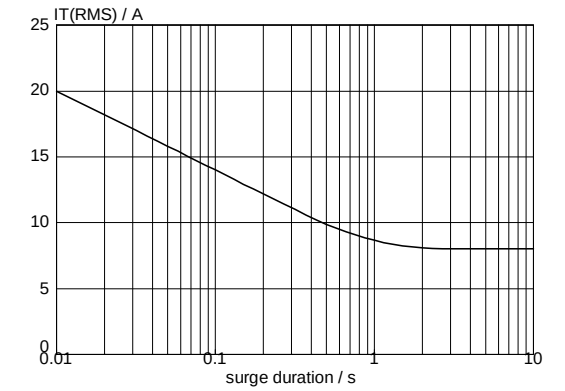


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{mb} \leq 102^{\circ}C$.

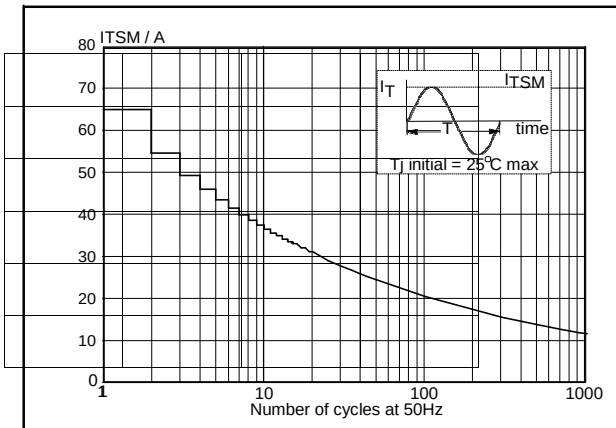


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM}, versus number of cycles, for sinusoidal currents, f = 50 Hz.

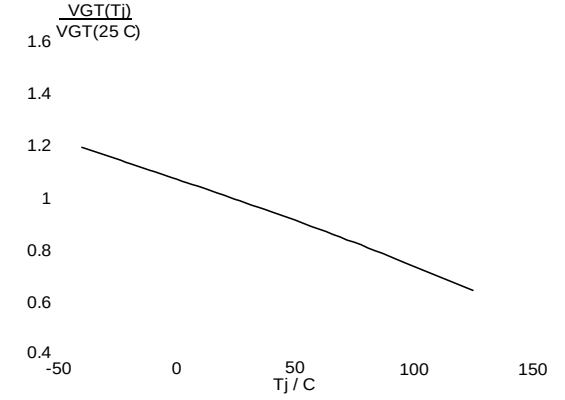


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/ V_{GT}(25^{\circ}C)$, versus junction temperature T_j

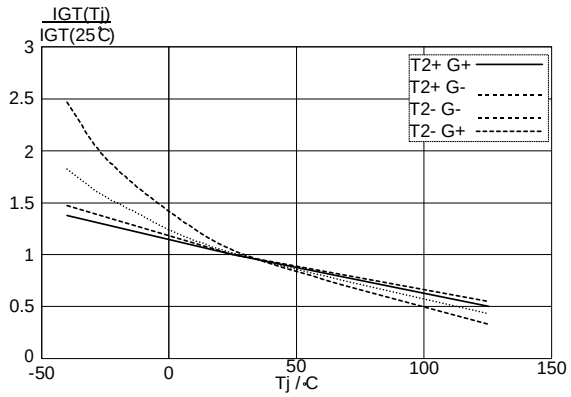


Fig.7. Normalised gate trigger current $I_{GT}(T_j)/ I_{GT}(25^{\circ}C)$, versus junction temperature T_j

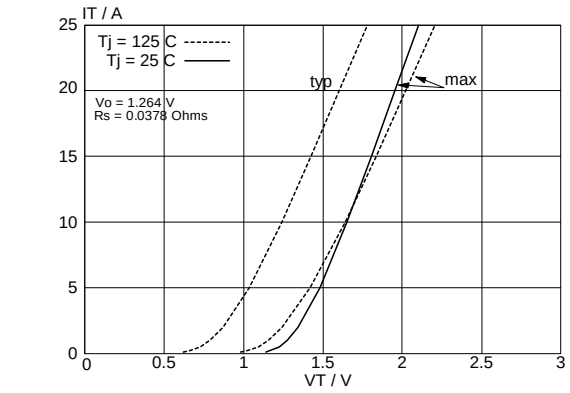


Fig.10. Typical and maximum on-state

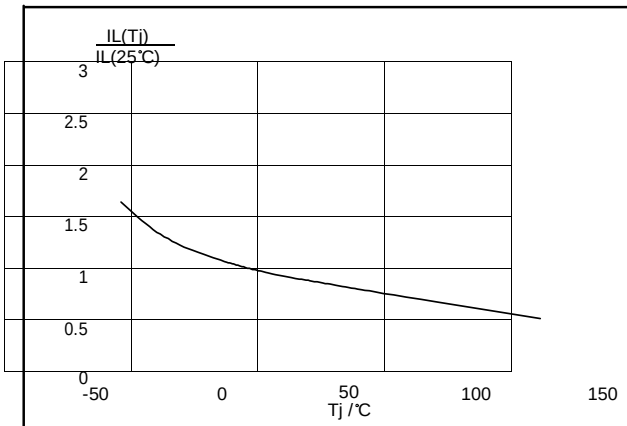


Fig.8. Normalised latching current $I_L(T_j)/ I_L(25^{\circ}C)$, versus junction temperature T_j.

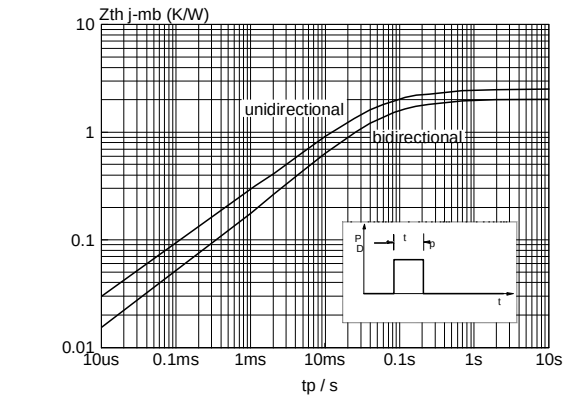


Fig.11. Transient thermal impedance $Z_{th\ j\text{-}mb}$, versus pulse width t_p.

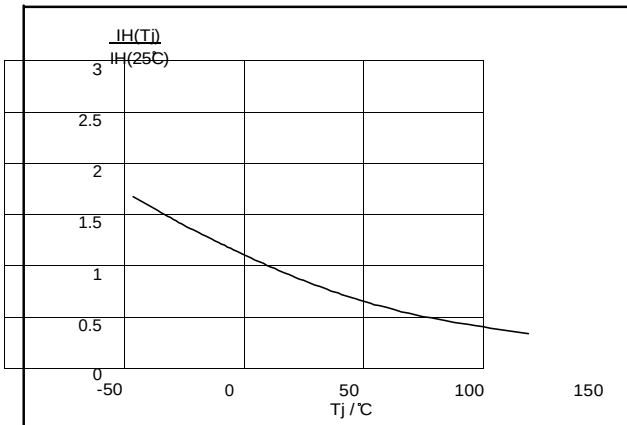


Fig.9. Normalised holding current $I_H(T_j)/ I_H(25^{\circ}C)$, versus junction temperature T_j.

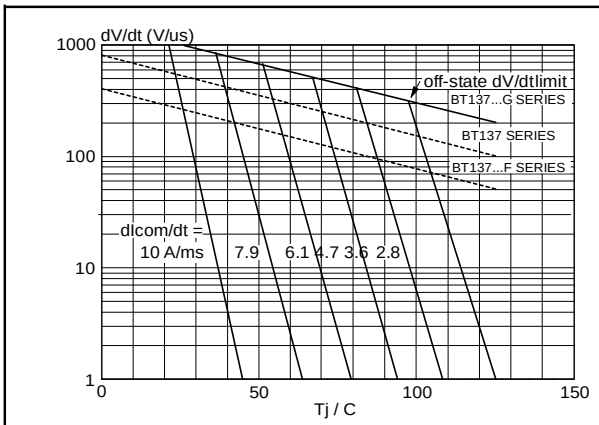


Fig.12. Typical commutation dV/dt versus junction temperature, parameter commutation dI_T/dt. The triac should commutate when the dV/dt is below the value on the appropriate curve for pre-commutation dI_T/dt.

MECHANICAL DATA

Dimensions in mm

Net Mass: 1.1 g

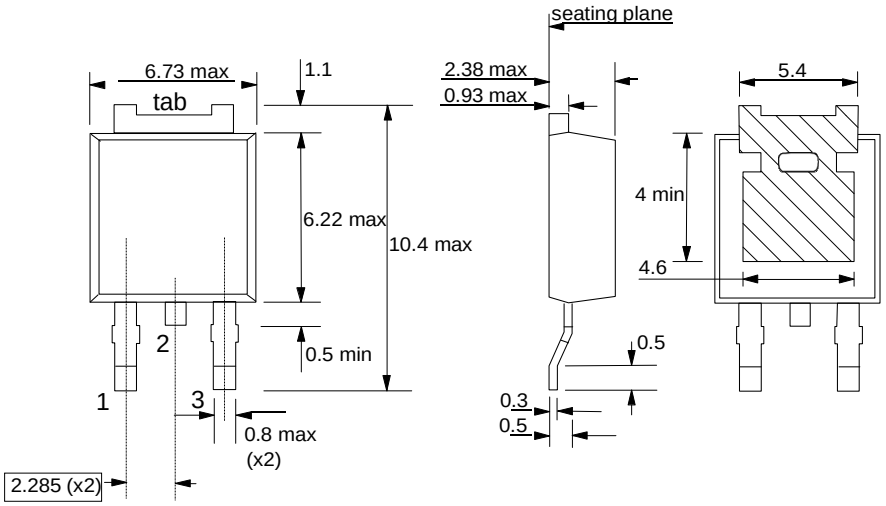


Fig.13. SOT428 : centre pin connected to tab.

MOUNTING INSTRUCTIONS

Dimensions in mm

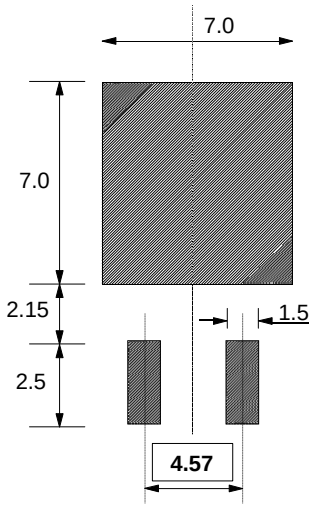


Fig.14. SOT428 : minimum pad sizes for surface mounting.

Notes

1. Plastic meets UL94 V0 at 1/8".